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Orderable: N/A	Designed for: Public Release	Mod. Date: 4/8/2016
TID #: PMP20070	Project Title: LM5022 Boost	
Number: PMP20070	Rev: A	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 1 of 2
Drawn By:	File: PMP20070_REVA.SchDoc	Size: B
Engineer: R. Sheehan	Contact: http://www.ti.com/support	



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H1 1
NY PMS 440 0025 PH

H2 1
NY PMS 440 0025 PH

H3 1
NY PMS 440 0025 PH

H4 1
NY PMS 440 0025 PH

H5
1902C

H6
1902C

H7
1902C

H8
1902C

DNP
FID1

DNP
FID2

DNP
FID3

PCB Number: PMP20070
PCB Rev: A

PCB
LOGO
FCC disclaimer

PCB
LOGO
ESD Susceptible

Label Table	
Variant	Label Text
001	

Orderable: N/A	Designed for: Public Release	Mod. Date: 2/25/2016	 TEXAS INSTRUMENTS http://www.ti.com © Texas Instruments 2015
TID #: PMP20070	Project Title: LM5022 Boost		
Number: PMP20070	Rev: A	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 2 of 2	
Drawn By: R. Sheehan	File: PMP20070_REVA_Hardware.SchDoc	Size: B	
Engineer: R. Sheehan	Contact: http://www.ti.com/support		

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